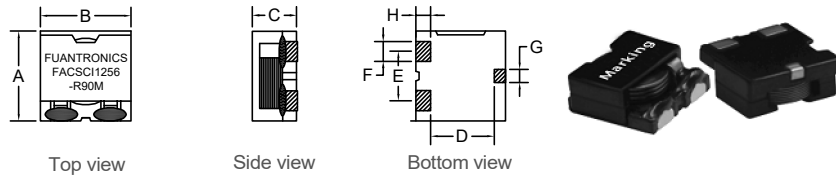


P/N: FACSCI1256-R90M

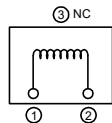


Outline Dimensions(Unit:mm)

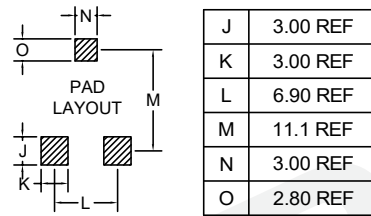


| A | B | C | D | E | F | G | H |
|------|-------|------|------|------|---------|------|------|
| Max | ±0.40 | Max | REF | REF | | REF | REF |
| 13.5 | 12.5 | 5.60 | 9.00 | 6.90 | 2.0-2.6 | 2.60 | 2.00 |

Electronical Schematic



Suggested Pad layout



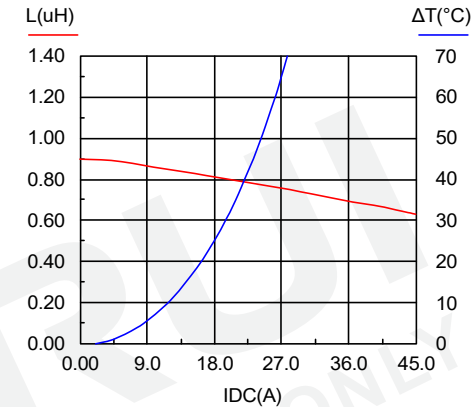
- ***Magnetic shielded structure: excellent resistance to electro magnetic interferenc(EMI).
- ***Assemblage design, sturdy structure.
- ***Small volume, high current, low magnetic loss, low ESR, small parasitic capacitance.
- ***Temperature rise current and saturation current is less influenced by environment.

Electrical Characteristics(@25°C)

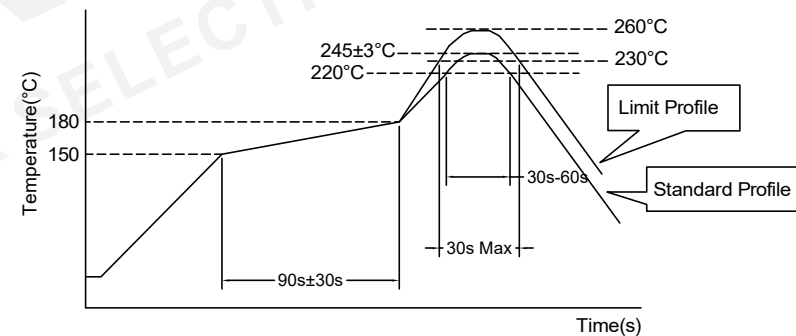
| Inductance 100KHz,0.1V | DC Resistor | Saturated current 28A | Temperature rise current 22A |
|---------------------------|-------------|-----------------------------|------------------------------------|
| 0.90uH±20% | 2.75mΩ Max | L(28A)=80%*L0A Typ | T≤40°C Typ |

- ***Saturation current: the actual value of DC current when the inductance decrease 20% of its initial value.
- ***Temperature rise current: the actual value of DC current when the temperature rise is ΔT40°C(Ta=25°C).
- ***Operating Temperature: -40°C~+125°C.
(Temperature rise included)
- ***Storage Temperature: -40°C~+125°C.
- ***Storage Humidity:RH10%~70%.

Saturation current VS temperature rise current curve:



Recommended Soldering Temperature Graph.



| | Standard Profile | Standard Profile |
|------------------|---------------------|---------------------|
| Pre-heating | 150~180°C,90s±30s | |
| Heating | above 220°C,30s-60s | above 240°C,30s Max |
| Peak temperature | 245°C±3°C | 260°C,10s |
| Cycle of reflow | 2 times | 2 times |